

WHAT IS CLAIMED IS:

1. A substrate inspecting method to be executed between a first component mounting step of mounting a predetermined type of part on a printed circuit board and a second mounting step of mounting a component on a position with no component mounted of the substrate undergoing the first component mounting step, wherein

it is inspected on a substrate undergoing the first component mounting step whether a component mounted in the first component mounting step is included in a region corresponding to the component mounting position in the second component mounting step.

2. A substrate inspecting method to be executed between a first component mounting step of mounting a predetermined type of part on a printed circuit board and a second mounting step of mounting a component on a position with no component mounted of the substrate undergoing the first component mounting step, wherein

the following are executed: processing of imaging a substrate undergoing the first component mounting step whenever accepting the substrate, first inspection for determining on an obtained image whether the image of a component is included in a region corresponding to the component mounting position in the first component mounting step, and second inspection for determining

whether the image of a component mounted in the first component mounting step is included in a region corresponding to the component mounting position in the second component mounting step.

3. A substrate inspecting method to be executed between a first component mounting step of mounting a predetermined type of part on a printed circuit board and a second mounting step of mounting a component on a position with no component mounted of a substrate undergoing the first component mounting step, wherein

the following are executed whenever accepting the substrate: processing of imaging a substrate undergoing the first component mounting step, first inspection for determining on an obtained image whether the image of a component is included in a region corresponding to the component mounting position in the first component mounting step, and second inspection for determining whether the image of a component mounted in the first component mounting step is included in a region corresponding to the component mounting position in the second component mounting step when it is determined in the first inspection that the image of a component is not correctly included in a predetermined region.

4. A substrate inspecting method to be executed between a first component mounting step of mounting a

predetermined type of part on a printed circuit board and a second mounting step of mounting a component on a position with no component mounted of the substrate undergoing the first component mounting step, wherein

processing of imaging a substrate undergoing the first component mounting step and first inspection for determining whether the image of a component is included in a region corresponding to the component mounting position in the first component mounting step are executed whenever accepting the substrate under a state in which it is possible to accept the information showing the expiry date of a component-mounting implement used in the first component mounting step, and

correspondingly to input of the information, second inspection for determining whether the image of a component mounted in the first component mounting step is included in a region corresponding to the component mounting position in the second component mounting step is executed for a predetermined number of substrates to be subsequently accepted together with the imaging and the first inspection.

5. A substrate inspecting method to be executed between a first component mounting step of mounting a predetermined type of part on a printed circuit board and a second mounting step of mounting a component on a

position with no component mounted of a substrate undergoing the first component mounting step, wherein processing of imaging a substrate undergoing the first component mounting step and first inspection for determining on an obtained image whether the image of a component is included in a region corresponding to the component mounting position in the first component mounting step are executed whenever accepting the substrate under a state in which it is possible to accept the information showing that the solder printed state of the substrate is deteriorated, and

correspondingly to input of the information, second inspection for determining whether the image of a component mounted in the first component mounting step is included in a region corresponding to the component mounting position in the second component mounting step is executed for a predetermined number of substrates to be subsequently accepted together with the imaging and the first inspection.

6. The substrate inspecting method according to Claim 1, wherein

the first component mounting step is a step of mounting a chip component.

7. The substrate inspecting method according to Claim 1, wherein

the second component mounting step is a step of mounting a odd-shaped component.

8. A substrate inspecting apparatus set between a first component mounting step of mounting a predetermined type of component on a printed circuit board and a second component mounting step of mounting a component on a position of a substrate undergoing the first component mounting step where a component is not mounted in the first component mounting step to inspect the component mounted state of the substrate undergoing the first component mounting step, comprising:

an imaging part for imaging a substrate to be inspected;

a storing part for storing inspection data for executing first inspection for determining on an image obtained from the imaging part whether the image of a component is included in a region corresponding to the component mounting position in the first component mounting step and the inspection data for executing second inspection for determining whether the image of a component mounted in the first component mounting step is included in a region corresponding to the component mounting position in the second component mounting step;

an inputting part for inputting a condition for executing the second inspection;

an inspection executing part for processing an image obtained by the imaging part by using inspection data for the first inspection and processing the image by using the inspection data for the second inspection when the condition input from the inputting part is effected; and

an outputting part for outputting the result of an inspection by the inspection executing part.